

Gap Pad® 3000S30

Thermally Conductive, Reinforced, Soft “S-Class” Gap Filling Material

Features and Benefits

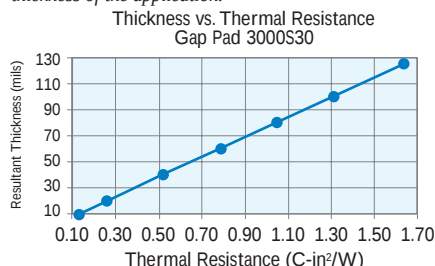
- Thermal conductivity: 3.0 W/m-K
- Low “S-Class” thermal resistance at very low pressures
- Highly conformable, “S-Class” softness
- Designed for low-stress applications
- Fiberglass reinforced for puncture, shear and tear resistance



Gap Pad 3000S30 is a soft gap filling material rated at a thermal conductivity of 3 W/m-K. The material offers exceptional thermal performance at low pressures due to an all-new 3 W/m-K filler package and low-modulus resin formulation. It is reinforced to enhance material handling, puncture, shear and tear resistance. It is well suited for high performance, low-stress applications that typically use fixed standoff or clip mounting. Gap Pad 3000S30 maintains a conformable yet elastic nature that allows for excellent interfacing and wet-out characteristics, even to surfaces with high roughness and/or topography.

Gap Pad 3000S30 is offered with natural inherent tack on both sides of the material, eliminating the need for thermally-impeding adhesive layers. The material's natural inherent tack allows for stick-in-place characteristics during assembly. Gap Pad 3000S30 is supplied with protective liners on both sides. The top side has reduced tack for ease of handling.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 3000S30			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Light Blue	Light Blue	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	—
Thickness (inch) / (mm)	0.010 to 0.125	0.254 to 3.175	ASTM D374
Inherent Surface Tack (1- or 2-sided)	2	2	—
Density (g/cc)	3.2	3.2	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	30	30	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	26	180	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>3000	>3000	ASTM D149
Dielectric Constant (1000 Hz)	7.0	7.0	ASTM D150
Volume Resistivity (Ohm-meter)	10 ⁹	10 ⁹	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	3.0	3.0	ASTM D5470

1) Thirty second delay value Shore 00 hardness scale.
2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch. For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

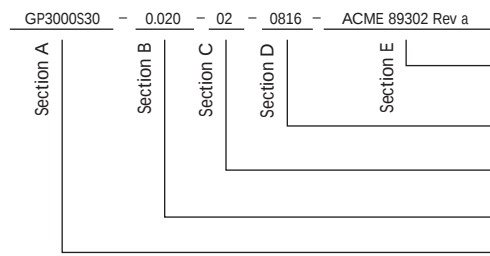
Typical Applications:

- Processors
- Server S-RAMs
- Mass storage drives
- Wireline / wireless communications hardware
- Notebook computers
- BGA packages
- Power conversion

Configurations Available:

- Sheet form and die-cut parts available

Building a Part Number



Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

0816 = Standard sheet size 8" x 16", or
00 = custom configuration

02 = Natural tack, both sides

Standard thicknesses available: 0.010", 0.015", 0.020",
0.040", 0.060", 0.080", 0.100", 0.125"

GP3000S30 = Gap Pad 3000S30 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others



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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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